

## **REMARKS**

Claims 1, 3-5 and new Claims 6 and 7 are now pending in the application. Claim 2 is canceled. The Examiner is respectfully requested to reconsider and withdraw the rejections in view of the amendments and remarks contained herein.

Applicant would like to thank the Examiner for the courtesies extended to their representative, Thomas Krul, during a telephonic interview on June 10, 2004 to discuss this matter. During the interview, Applicant presented arguments in favor of patentability along the lines set forth below. The Examiner noted the arguments were persuasive, and that both further review of the Goto et al. (U.S. Patent 6,042,894) reference as well as an additional search appeared to be required.

## **SPECIFICATION**

The abstract of the specification stands objected to for certain informalities. Applicant has amended the abstract according to the Examiner's suggestions. Therefore, reconsideration and withdrawal of this objection are respectfully requested.

## **REJECTION UNDER 35 U.S.C. § 102**

Claims 1-5 stand rejected under 35 U.S.C. § 102(e) as being anticipated by Goto et al. (U.S. Pat. No. 6,042,894). This rejection is respectfully traversed.

It is initially noted Claim 1 has been amended to recite in part "wherein the first adhesive layer and the second adhesive layer are formed of the same material" and Claim 2 has therefore been canceled.

Goto et al. '894 discloses a process wherein electroconductive particles are applied "on [a] sticking material surface and fixing them with said electroconductive particles being oriented in the plane direction on the adhesive surface, and then coating thereon a film-forming resin solution". See column 8, lines 5-11. The film-forming resin solution is specifically noted as being "incompatible with the adhesive" (See column 8, lines 11-12). This is further noted in the specification wherein the film forming resin is "incompatible with the sticking material" (see column 5, lines 10-13) and as "a photocurable film-forming resin incompatible with the adhesive" (see column 8, lines 30-31). Goto et al. defines "incompatible" in column 11, lines 34-57.

The electroconductive resin film which is the result of the Goto et al. process provides "electroconductive particles exposed on both sides of the film" which is created by curing the film-forming resin and subsequently dissolving portions of the film-forming resin using a solvent. See column 8, lines 28-42. The solvent therefore must be selected so it cannot affect the adhesive layer. The two resins "don't form a homogenous mixture" (see column 11, lines 35-37).

Goto et al. '894 fails to disclose the additional element of amended Claim 1 that "the first adhesive layer and the second adhesive layer are formed of the same material". Goto et al. therefore does not anticipate amended Claim 1. The Examiner is respectfully requested to withdraw the 35 U.S.C. § 102(e) rejection of Claim 1. Because each of Claims 3-5 depend from amended Claim 1, Goto et al. therefore does not anticipate Claims 3-5 for at least the same reasons. The Examiner is respectfully requested to withdraw the 35 U.S.C. § 102(e) rejections of Claims 3-5.

Further, Goto et al. does not anticipate Claim 3 for the additional reasons noted below. As noted above Goto et al. discloses that a sticking layer and a film-forming resin layer are used. Goto et al. further discloses that the sticking layer is an “anisotropically electroconductive adhesive” and that the electroconductive particles and the adhesive surface can be electrically charged with different electric charges to help position the electroconductive particles. See column 9, lines 9-12. This directly contrasts with Claim 3 which recites in part “the material of both the first adhesive layer and the second adhesive layer is an insulating adhesive agent”. Goto et al. therefore does not anticipate Claim 3.

Still further, Goto et al. does not anticipate Claim 4 for the additional reasons noted below. Applicant respectfully disagrees with the Examiner’s position with respect to Claim 4. The Examiner stated “The film forming resin is an insulating adhesive and the electroconductive particles are buried in the sticking layer to a depth of half or less of the particle size of the electroconductive particles (column 6, lines 10-11 and 35-39)”. Goto et al. does not disclose that the electroconductive particles are  $\frac{1}{2}$  or less than the thickness of the sticking layer (adhesive). Applicant notes that Goto et al. applies the electroconductive particles onto the sticking layer or rolls the electroconductive particles into the sticking layer to hold the electroconductive particles. In one embodiment (Figure 1P) the electroconductive particle size is greater than a thickness of the adhesive. In other embodiments, the electroconductive particles are disposed within the resulting electroconductive resin film which does not permit determination of the thickness of the separate sticking layer or a mathematical comparison of the sticking layer to the size of the electroconductive particles. Goto et al. therefore does not disclose that “the particle

diameter of the electrically conductive particles is smaller than  $\frac{1}{2}$  of the thickness of the first adhesive layer” as recited in Claim 4.

Yet further, Goto et al. does not anticipate Claim 5 for the additional reasons noted below. Goto et al. does not disclose that the electroconductive particles are both within the adhesive layer and adjacent to an interface of the adhesive layer and the film forming resin. Goto et al. therefore does not disclose the additional elements of amended Claim 5 of “the plurality of electrically conductive particles are unevenly distributed within the first adhesive layer and adjacent to an interface of the first and second adhesive layers”. Goto et al. therefore does not anticipate amended Claim 5.

#### **NEW CLAIMS**

New Claim 6 is presented herein. Claim 6 calls for the electrically conductive particles to be fixed within the first adhesive layer and adjacent a lamination surface of the first adhesive layer and that the conductive particles are aligned at a terminal connection position within the conductive adhesive agent. Favorable consideration of new Claim 6 is respectfully requested.

New Claim 7 is also presented herein. Claim 7 calls for a plurality of electrically conductive particles included within the first adhesive layer and that the electrically conductive particles are unevenly distributed along a second adhesive layer facing side of the first adhesive layer. Favorable consideration of new Claim 7 is respectfully requested.

**INFORMATION DISCLOSURE STATEMENT FORM HDP 1449**

The Examiner forwarded a copy of HDP Form 1449 submitted with the original application filing documents on the November 4, 2003 filing date of the subject application. It was noted on the copy of HDP Form 1449 that the 8 Japanese documents listed were not provided or were not present in the parent file. Contrary to the Examiner's position, all of the 8 Japanese documents were submitted during prosecution of the parent application. Applicants provide herewith copies of documents from the parent application, serial number 09/171,924 documenting the submittal and receipt by the U.S. Patent and Trademark Office of the subject Japanese documents.

### CONCLUSION

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action, and as such, the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

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